

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC050N10NS5	**Issued**	11. April 2021
MA#	MA005344511		
Package	PG-TDSON-8-50	**Weight***	106.97 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.185	1.11	1.11	11082	11082
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		127	
	non noble metal	zinc	7440-66-6	0.055	0.05		510	
	non noble metal	iron	7439-89-6	1.090	1.02		10193	
	non noble metal	copper	7440-50-8	44.271	41.38	42.46	413885	424715
wire	noble metal	gold	7440-57-5	0.041	0.04	0.04	386	386
encapsulation	organic material	carbon black	1333-86-4	0.084	0.08		786	
	plastics	epoxy resin	-	3.869	3.62		36171	
	inorganic material	silicondioxide	60676-86-0	38.102	35.62	39.32	356205	393162
leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11814	11814
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	271	271
solder	noble metal	silver	7440-22-4	0.041	0.04		384	
	non noble metal	tin	7440-31-5	0.082	0.08		767	
	non noble metal	lead	7439-92-1	1.518	1.42	1.54	14191	15342
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		172	
	non noble metal	iron	7439-89-6	0.368	0.34		3437	
	non noble metal	copper	7440-50-8	14.930	13.96	14.32	139576	143228
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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